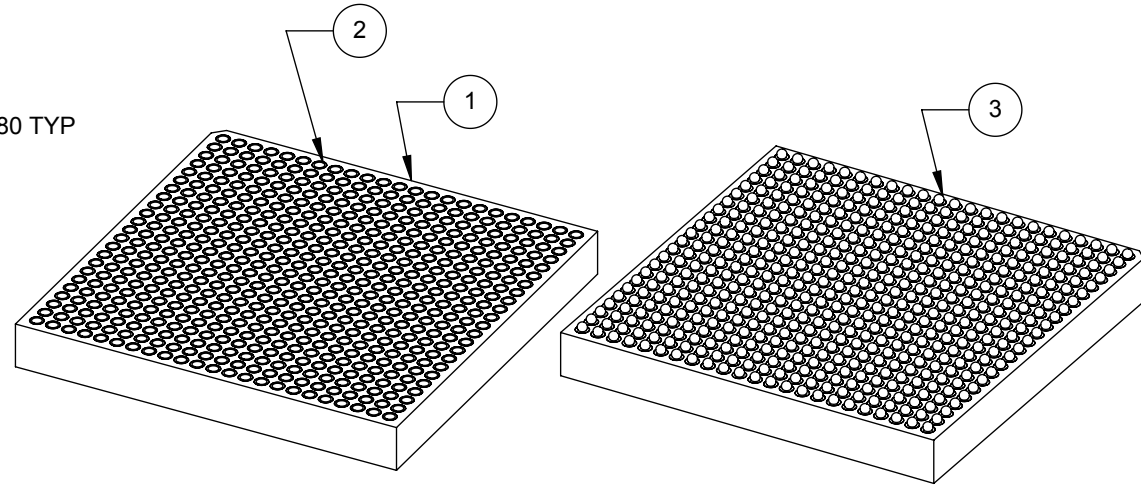
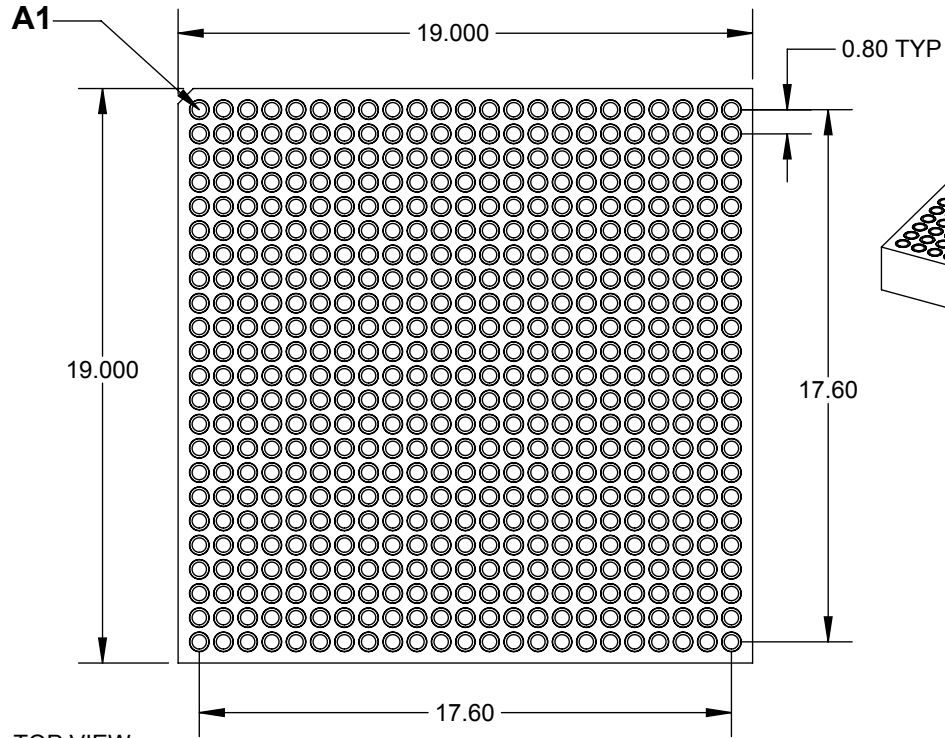
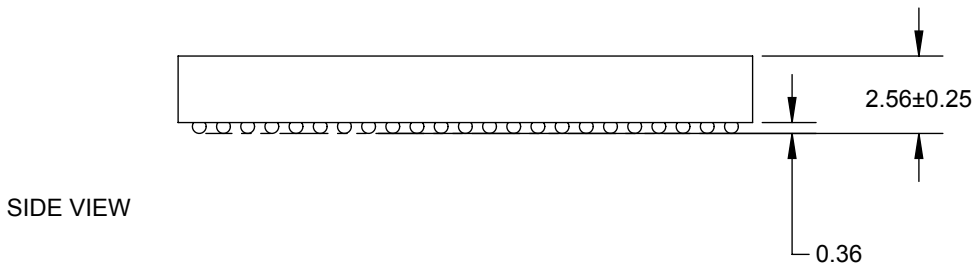


# U.S. Patent No. 8,091,222 B2



ITEM NO.	DESCRIPTION
1	High Temp Substrate
2	High Density Giga-Snap Receptacle
3	Solder Ball, 0.4572mm dia (See Table)




PART NO. SUFFIX	SOLDER BALL ALLOY
-64	Sn63Pb37
-64F*	Sn96.5Ag3.0Cu0.5
*RoHS Compliant	

## Description: Giga-snaP BGA SMT Foot

Primary dimension units are millimeters, Secondary dimension units are [inches].

Tolerances: Hole diameters  $\pm 0.03\text{mm}$  [ $\pm 0.001"$ ], Pitches (from true position)  $\pm 0.025\text{mm}$  [ $\pm 0.001"$ ], substrate thickness tolerance  $\pm 10\%$ , all other tolerances  $\pm 0.13\text{mm}$  [ $\pm 0.005"$ ] unless stated otherwise. Materials and specifications are subject to change without notice.


<b>SF-BGA529D-B-64 Drawing</b> <b>SF-BGA529D-B-64F Drawing</b>  Ironwood Electronics, Inc. Tele: (800) 404-0204 www.ironwoodelectronics.com	Material: N/A Finish: N/A Weight: N/A	STATUS: Released	SHEET: 1 OF 2	REV. C
		DRAWN BY: M. Raske	SCALE: 4:1	
		FILE: SF-BGA529D-B-64 Dwg	DATE: 04/11/2012	

Rev	Date	Initials	Description
A	4/11/12	-	Original
B	7/1/14	MR	Corrected title block part numbers
C	7/7/15	MT/OA	updated materials to generic definitions

### Description: Revision History

Primary dimension units are millimeters, Secondary dimension units are [inches].

Tolerances: Hole diameters  $\pm 0.03\text{mm}$  [ $\pm 0.001"$ ], Pitches (from true position)  $\pm 0.025\text{mm}$  [ $\pm 0.001"$ ], substrate thickness tolerance  $\pm 10\%$ , all other tolerances  $\pm 0.13\text{mm}$  [ $\pm 0.005"$ ] unless stated otherwise. Materials and specifications are subject to change without notice.

<b>SF-BGA529D-B-64 Drawing</b>		Material: Finish: Weight:	STATUS: Released	SHEET: 2 OF 2	REV. C
<b>SF-BGA529D-B-64F Drawing</b>			DRAWN BY: M. Raske	SCALE: 1:1	
	Ironwood Electronics, Inc. Tele: (800) 404-0204 www.ironwoodelectronics.com		FILE: SF-BGA529D-B-64 Dwg	DATE: 04/11/2012	